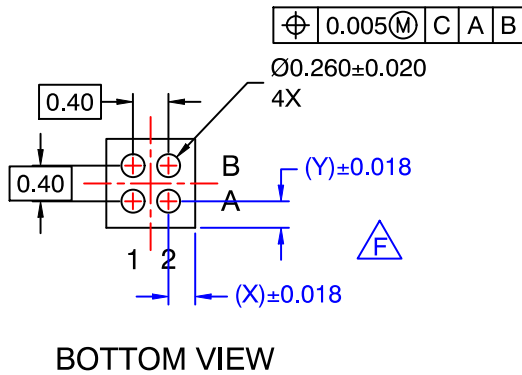
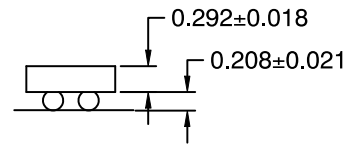
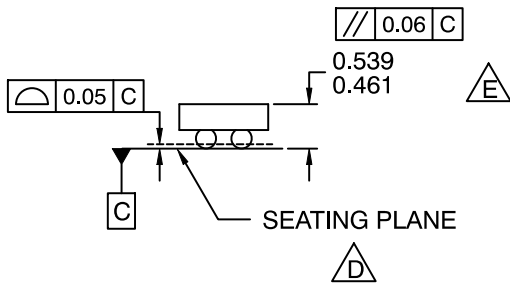
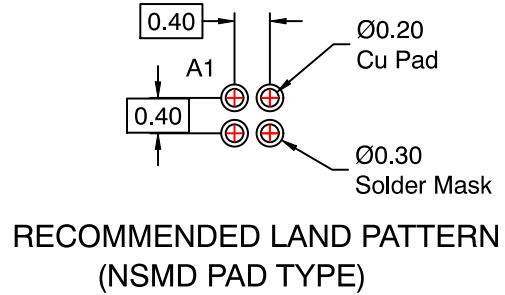
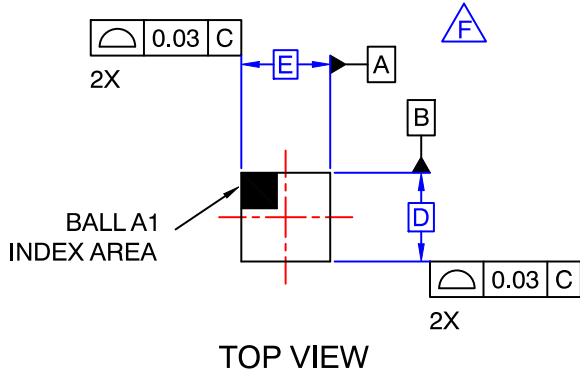




**WLCSP4 0.8x0.8x0.5**  
CASE 567QP  
ISSUE O

DATE 31 OCT 2016



**NOTES:**

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 1994.
- △ D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- △ E. PACKAGE NOMINAL HEIGHT IS 500 MICRONS ±39 MICRONS (461–539 MICRONS).
- △ F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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<b>DESCRIPTION:</b>	<b>WLCSP4 0.8x0.8x0.5</b>	<b>PAGE 1 OF 1</b>

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